



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-07-10
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EYE3*V876AAJ	A	ZS1A	2013-07-10
Amount	UoM	Unit type	ST ECOPACK Grade	
27.942	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	3x2.2.95x1.1	8	gull wing	
Comment	Package: MSOP/TSSOP 8 BODY3.00 PITCH0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EYE3*V876AAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	0.447	mg	Supplier	Silicon Die	Silicone	7440-21-3		0.44	mg	984340	15747
Silicon Die			mg	Supplier	Passivation	Gamma-butyrolactone	96-48-0		0.005	mg	11186	179
Silicon Die			mg	Supplier	Passivation	Polyhydroxyamide	55295-98-2		0.002	mg	4474	72
Leadframe	Copper and its alloy	9.898	mg	Supplier	Alloy	Copper	7440-50-8		9.536	mg	963427	341278
Leadframe			mg	Supplier	Alloy	Iron	7439-89-6		0.223	mg	22530	7981
Leadframe			mg	Supplier	Alloy	Phosphorus	7723-14-0		0.002	mg	202	72
Leadframe			mg	Supplier	Alloy	Zinc	7440-66-6		0.012	mg	1212	429
Leadframe			mg	Supplier	Alloy	Nickel	7440-02-0		0.114	mg	11517	4080
Leadframe			mg	Supplier	Alloy	Palladium	7440-05-3		0.01	mg	1010	358
Leadframe			mg	Supplier	Alloy	Gold	7440-57-5		0.001	mg	101	36
Die Attach	Other Organic Material	0.621	mg	Supplier	Glue	Silver	7440-22-4		0.499	mg	803543	17858
Die Attach			mg	Supplier	Glue	Carbocyclic Acrylates	proprietary		0.062	mg	99839	2219
Die Attach			mg	Supplier	Glue	Bismaleimide resin	proprietary		0.019	mg	30596	680
Die Attach			mg	Supplier	Glue	2-preponic acid, 2-methyl	68586-19-6		0.019	mg	30596	680
Die Attach			mg	Supplier	Glue	Additive	proprietary		0.019	mg	30596	680
Die Attach			mg	Supplier	Glue	Dicumyl peroxide	80-43-3		0.003	mg	4831	107
Bonding Wire	Other Inorganic Material	0.31	mg	Supplier	Bonding Wire	Gold	7440-57-5		0.31	mg	1000000	11094
Encapsulation	Other Organic Material	16.666	mg	Supplier	Molding Compound	Epoxy Resin-1	Proprietary		0.501	mg	30061	17930
Encapsulation			mg	Supplier	Molding Compound	Epoxy Resin-2	Proprietary		0.501	mg	30061	17930
Encapsulation			mg	Supplier	Molding Compound	Phenol resin	Proprietary		0.752	mg	45122	26913
Encapsulation			mg	Supplier	Molding Compound	Silica	60676-86-0		14.879	mg	892776	532496
Encapsulation			mg	Supplier	Molding Compound	Carbon Black	1333-86-4		0.033	mg	1980	1181